L Number	Hits	Search Text	DB	Time stamp
1	1441	(349/155,156).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 10:59
2	1609	(427/77,105,106,133).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:00
3	524	(264/61,272.11).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:00
4	2761	438/624.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:00
5	1601	445/24.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:00
6	532	(216/25,33).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:00
7	1190	264/129.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:01
9	341052	spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:01
10	723	positive adj mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:01
11	142752	photoresist photo-resist photo adj resist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:02
13	7	(positive adj mold) same (photoresist photo-resist photo adj resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:02
14	0	spacer same ((positive adj mold) near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:02

15	0	spacer and ((positive adj mold) near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:02
12	7	(positive adj mold) near10 (photoresist photo-resist photo adj resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:05
16	423828	photograph$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:05
17	5	(positive adj mold) same photograph$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:06
18	1095	epoxy adj bisphenol	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:06
19	6090	novolac adj resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:06
21	36	(epoxy adj bisphenol) near5 (novolac adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:06
22	0	(positive adj mold) same ((epoxy adj bisphenol) near5 (novolac adj resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:06
23	0	(positive adj mold) and ((epoxy adj bisphenol) near5 (novolac adj resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07
24	0	positive near10 ((epoxy adj bisphenol) near5 (novolac adj resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07
25	15563	positive near10 (photoresist photo-resist photo adj resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07
27	10	((427/77,105,106,133).ccls.) and (positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07

28	1	((264/61,272.11).ccls.) and (positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07
29	70	438/624.ccls. and (positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07
30	77	445/24.ccls. and (positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07
32	1	264/129.ccls. and (positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:07
26	32	((349/155,156).ccls.) and (positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11
33	774644	mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11
34	42	mold near10 positive near10 (photoresist photo-resist photo adj resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11
35	0	((349/155,156).ccls.) and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11
36	0	((427/77,105,106,133).ccls.) and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11
37	0	((264/61,272.11).ccls.) and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11
38	0	438/624.ccls. and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11
39	0	445/24.ccls. and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:11

41	0	264/129.ccls. and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:12
40	1	((216/25,33).ccls.) and (mold near10 positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:12
42	16483	sol-gel solgel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:12
43	6	((349/155,156).ccls.) and (sol-gel solgel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
44	90	spacer same (sol-gel solgel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
45	0	((427/77,105,106,133).ccls.) and (spacer same (sol-gel solgel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
46	0	((264/61,272.11).ccls.) and (spacer same (sol-gel solgel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
47	0	438/624.ccls. and (spacer same (sol-gel solgel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
49	0	((216/25,33).ccls.) and (spacer same (sol-gel solgel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
50	1	264/129.ccls. and (spacer same (sol-gel solgel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
48	5	445/24.ccls. and (spacer same (sol-gel solgel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:13
31	37	((216/25,33).ccls.) and (positive near10 (photoresist photo-resist photo adj resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 11:18

L Number	Hits	Search Text	DB	Time stamp
1	1002905	positive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:07
2	126567	photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:07
3	1020	epoxy adj bisphenol	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:08
4	4222	novolac adj resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:10
5	35	(epoxy adj bisphenol) near5 (novolac adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:10
6	257	positive same photoresist same ((epoxy adj bisphenol) (novolac adj resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:10
7	341052	spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:10
8	2	(positive same photoresist same ((epoxy adj bisphenol) (novolac adj resin))) same spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:10
9	13	(positive same photoresist same ((epoxy adj bisphenol) (novolac adj resin))) and spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:22
10	3220	positive near5 mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:22
12	1	spacer and ((positive near5 mold) same photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:23
11	34	(positive near5 mold) same photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 13:24

L Number	Hits	Search Text	DB	Time stamp
1	8846	positive near5 photoresist	USPAT; JPO	2004/03/30 14:31
2	218550	spacer	USPAT; JPO	2004/03/30 14:31
3	845	(positive near5 photoresist) and spacer	USPAT; JPO	2004/03/30 14:32
4	107	(positive near5 photoresist) same spacer	USPAT; JPO	2004/03/30 14:32
6	341648	mold mould	USPAT; JPO	2004/03/30 14:32
7	18	(positive near5 photoresist) near10 (mold mould)	USPAT; JPO	2004/03/30 14:32
5	62	(positive near5 photoresist) near10 spacer	USPAT; JPO	2004/03/30 14:47
8	449	positive adj (mold mould)	USPAT; JPO	2004/03/30 14:47
9	2	spacer near10 (positive adj (mold mould))	USPAT; JPO	2004/03/30 14:49
10	1	("5930890").PN.	USPAT	2004/03/30 14:50
11	95928	photolithograph$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 14:51
12	1	(positive adj (mold mould)) same photolithograph$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 14:51
13	375	photolithograph$5 near10 (positive near5 photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 14:52
14	5	spacer same (photolithograph$5 near10 (positive near5 photoresist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 14:52

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1	INZZ	positive ADJ (mold OR mould)	unrestricted	3	show titles
2	INZZ	photoresist	unrestricted	7438	show titles
3	INZZ	1 AND 2	unrestricted	0	-
4	INZZ	positive ADJ mold	unrestricted	2	show titles
5	INZZ	2 AND 4	unrestricted	0	-

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- Classification codes A: Physics, 4-5
- Classification codes A: Physics, 6
- Classification codes A: Physics, 7
- Classification codes A: Physics, 8
- Classification codes A: Physics, 9
- Classification codes B: Electrical & Electronics, 0-5
- Classification codes B: Electrical & Electronics, 6-9
- Classification codes C: Computer & Control, 0-9
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